Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: HYC5 (D3A) 005 SC70 NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	3.46	(mg) Total	Mold Compound	% ot Total Weight	54.97
Silica, vitreous	60676-86-0	Mold Compound	46.725	2.944	467,245		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.367	0.212	33,669		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.367	0.212	33,669		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.347	0.085	13,468		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.165	0.010	1,649		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	39.747	2.504	397,471		,	Total	100.00	
Iron	7439-89-6	Lead Frame	0.940	0.059	9.396	2.57	(mg) Total	Lead Frame	% of Total Weight	40.85
Phosphorous	7723-14-0	Lead Frame	0.102	0.006	1.021	-	Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-0	Lead Frame	0.061	0.004	613		Iron	7439-89-6	2.30	
Silver (Ag)	7440-22-4	Die Attach	0.620	0.039	6,202		Phosphorous	7723-14-0	0.25	
Proprietary Resin	Trade Secret	Die Attach	0.146	0.009	1,462		Zinc (Metal)	7440-66-0	0.15	
Proprietary Curing agent & Hardener	Trade Secret	Die Attach	0.024	0.003	237		Ziric (Wetai)	Total	100.00	
				0.089	14,200	0.05	() T-1-1			0.70
Silicon	7440-21-3	Chip (Die)	1.420			0.05	(mg) Total	Die Attach	% of Total Weight	0.79
Gold	7440-57-5	Wire Bond	0.130	0.008	1,300		Silver (Ag)	7440-22-4	78.50	
Nickel	7440-02-0	Plating on external leads (pins)	1.656	0.104	16,560		Proprietary Resin	Trade Secret	18.50	
Palladium	7440-05-3	Plating on external leads (pins)	0.092	0.006	920	Prop	rietary Curing agent & Hard	Trade Secret	3.00	
					920		•			
Gold	7440-57-5	Plating on external leads (pins)	0.092	0.006	920			Total	100.00	
Gold	7440-57-5	Plating on external leads (pins)  TOTALS:	0.092 <b>100.000</b>	0.006 <b>6.300</b>	1,000,000	0.09	Total (mg)	Chip (Die)	% of Total Weight	1.42
	0.0063 aterials comply v	TOTALS: g Total Mass vith EU Directives: 2002/95/EC (27 January 2003	100.000	6.300	1,000,000	0.09	Total (mg)  Doped Silicon			1.42
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